蓝箭电子
BLUE ROCKET ELECTRONICS

BRCS3415MC

Rev.B .Dec.-2024

DATA SHEET

/ Descriptions

SOT23-3 ṂṂ Ŀ S ꞩ MOS ʆ ῷ Ẕ ᄀ

P- CHANNEL MOSFET in a SOT23-3 Plastic Package.

/ Features

V_{DS} (V)=-20V I_D =-5.0A(V_{GS}= ± 10V)

$R_{DS(ON)}$< 40 mΩ,V_{GS}= -4.5V

$R_{DS(ON)}$< 53 mΩ,V_{GS}= -2.5V

ņ̇ ғ ᵝ HF Product.

/ Applications

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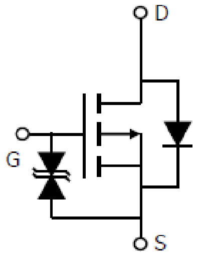
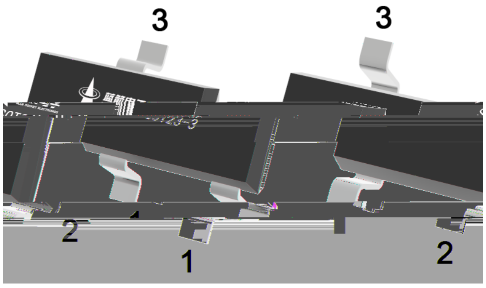
Load switch ı Battery protection.

/ Equivalent Circuit



/ Pinning



PIN1 χ G PIN 2 χ S PIN 3 χ D

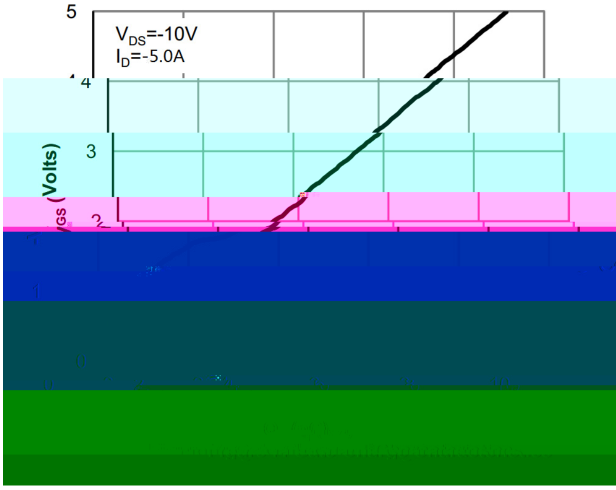
/ Marking

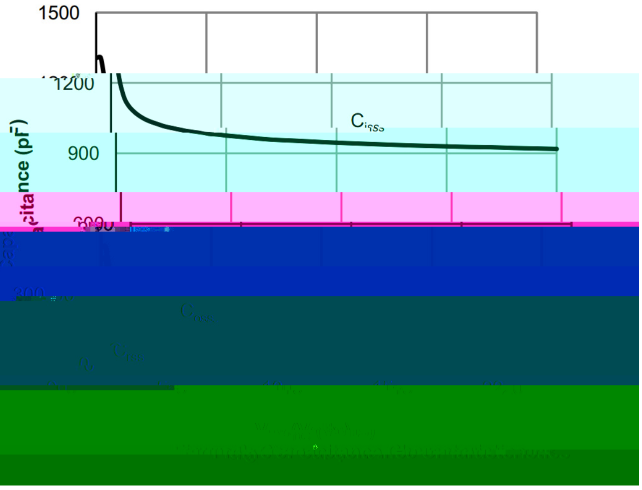
Marking	AFH

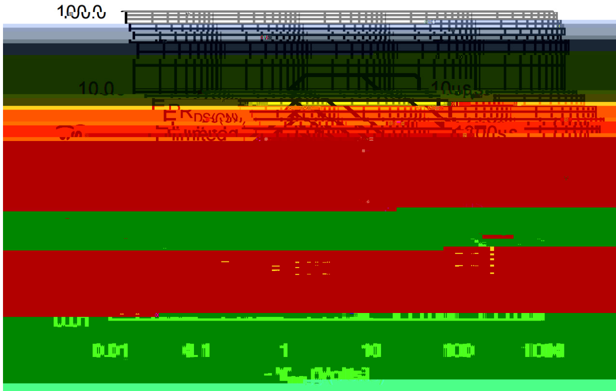
v ῼ Parameter	ɏ ᴺ Symbol	ῼӪ Rating	ᴅ Ɉ Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 10	V
Drain Current-Continuous	I_D	-5.0	A
Drain Current-Pulsed	I_{DM}		

/ Electrical Characteristic Curve

/ Electrical Characteristic Curve







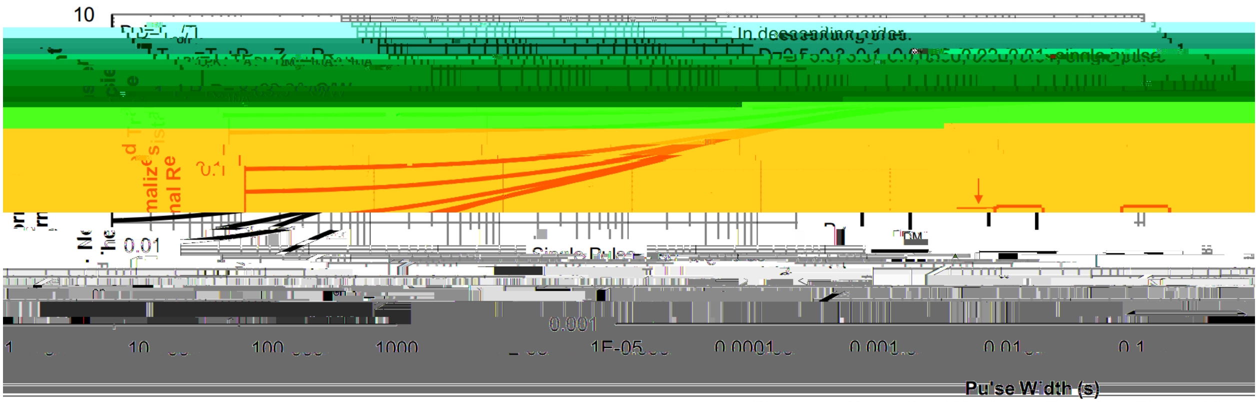
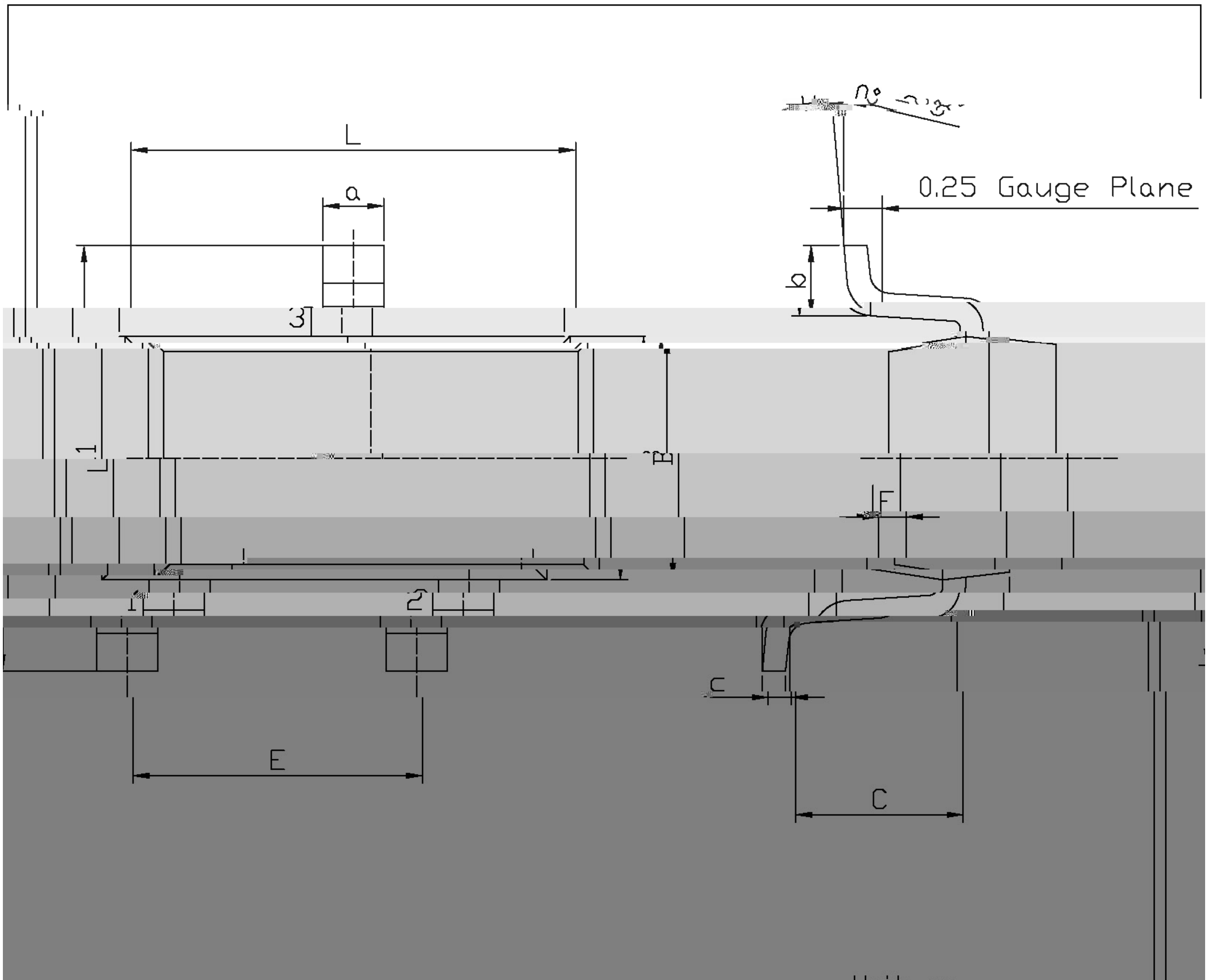


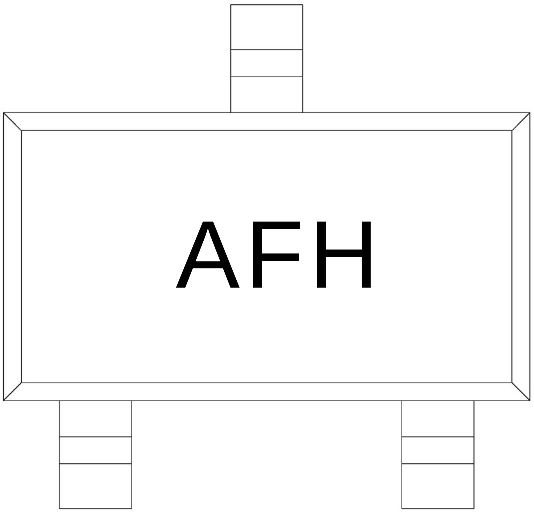
Figure 10: Normalized Maximum Transient Thermal Imp

/ Package Dimensions



Unit: mm

/ Marking Instructions



ب ˝ χ

H: ѭ ३ ᴎ Ꮒ

AF: ѭ ʒ ᴺ Ꮒ

Note:

H: Company Code

AF χ Product Type Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

ب ˝ χ
1 ỉ ♬ □ ŷ 150 Ḱ 180 ɫ ı ̀H ڙ 60 Ḱ 90sec;
2 Š Ӫ □ ŷ 245 ° 5 ɫ ı ̀H ڙ ΄Y ٨ ㎴ 5 ° 0.5sec;
3 ì ˙ ˥ ˛ ɔ ക ŷ ㎴ 2 Ḱ 10 ɫ /sec.

Note:
1.Preheating:150~180 ɫ , Time:60~90sec.
2.Peak Temp.:245 ° 5 ɫ , Duration:5 ° 0.5sec.
3. Cooling Speed: 2~10 ɫ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ŷ χ 260 ° 5 ɫ ̀H ڙ χ 10 ° 1 sec.

Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

ი ̀ γ Ŀ / REEL

Package Type	Units	Dimension	(unit mm[illegible]